



Customer Information Notification

202202017I : Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 25, 2022 **Effective date:** Feb 26, 2022

Management summary

Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Change Category

- | | | | | |
|--|--|--|--|---|
| ☐ Wafer
Fab
Process | ☐ Assembly
Process | ☐ Product Marking | ☐ Test
Process | ☐ Design |
| ☐ Wafer
Fab
Materials | ☐ Assembly
Materials | ☐ Mechanical
Specification | ☐ Test
Equipment | ☐ Errata |
| ☐ Wafer
Fab
Location | ☐ Assembly
Location | ☐ Packing/Shipping/Labeling | ☐ Test
Location | ☐ Electrical
spec./Test
coverage |
| ☐ Firmware | ☒ Other: Change of visual cosmetic appearance of product package | | | |

PCN Overview

Description

Our Assembly Site ATKH in Kaohsiung Taiwan is upgrading moulding equipment, which will result in visual cosmetic changes to product appearance for various QFP packages.

Reason

For affected products our Manufacturing Site in Taiwan is upgrading their moulding equipment.

Identification of Affected Products

Changed products can be identified by the added ejector marks and the date code in the final line(s) of the product's top marking. This date code is also shown on packing labelling.

Change over planning is indicated in the type list in the excel file attached to this mail notification

For example change over in wk2212 (wk 12 of 2022) means:

- Products with datecodes up to and including wk2211 will be produced on old equipment
- Products with datecodes wk2212 and later will be produced on new equipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document 'Attachment to NXP CIN 2022020171.pdf' with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Michiel Maas Geesteranus
Position	Assembly Change Coordinator
e-mail address	michiel.maas.geesteranus@NXP.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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High Tech Campus, 5656 AG Eindhoven, The Netherlands

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